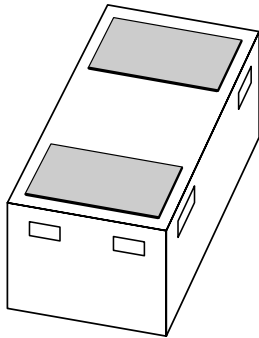


DATA SHEET



BAT54L Schottky barrier diode

Product data sheet

2003 Jun 23

Schottky barrier diode

BAT54L

FEATURES

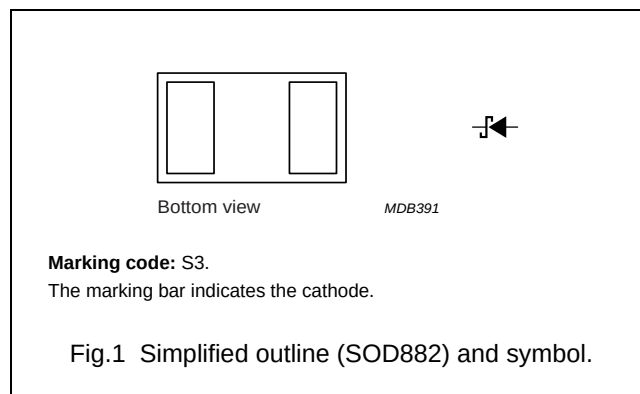
- Low forward voltage
- Leadless ultra small plastic package (1 mm × 0.6 mm × 0.5 mm)
- Boardspace 1.17 mm² (approx. 10% of SOT23)
- Power dissipation comparable to SOT23.

APPLICATIONS

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Mobile communication, digital (still) cameras, PDAs and PCMCIA cards.

DESCRIPTION

Planar Schottky barrier diode encapsulated in a SOD882 leadless ultra small plastic package.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		–	30	V
I_F	continuous forward current		–	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1s$; $\delta \leq 0.5$	–	300	mA
I_{FSM}	non-repetitive peak forward current	$t_p < 10\text{ ms}$	–	600	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$; note 1	–	250	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C

Note

1. Refer to SOD882 standard mounting conditions (footprint), FR4 printed-circuit board with 60 µm copper strip line.

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ELECTRICAL CHARACTERISTICS

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V_F	forward voltage	see Fig.2		
		$I_F = 0.1\text{ mA}$	240	mV
		$I_F = 1\text{ mA}$	320	mV
		$I_F = 10\text{ mA}$	400	mV
		$I_F = 30\text{ mA}$	500	mV
		$I_F = 100\text{ mA}$	800	mV
I_R	continuous reverse current	$V_R = 25\text{ V}$; see Fig.3; note 1	2	μA
C_d	diode capacitance	$V_R = 1\text{ V}$; $f = 1\text{ MHz}$; see Fig.4	10	pF

Note

1. Pulse test: $t_p = 300\text{ }\mu\text{s}$; $\delta = 0.02$.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\text{ j-a}}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Refer to SOD882 standard mounting conditions (footprint), FR4 printed-circuit board with $60\text{ }\mu\text{m}$ copper strip line.

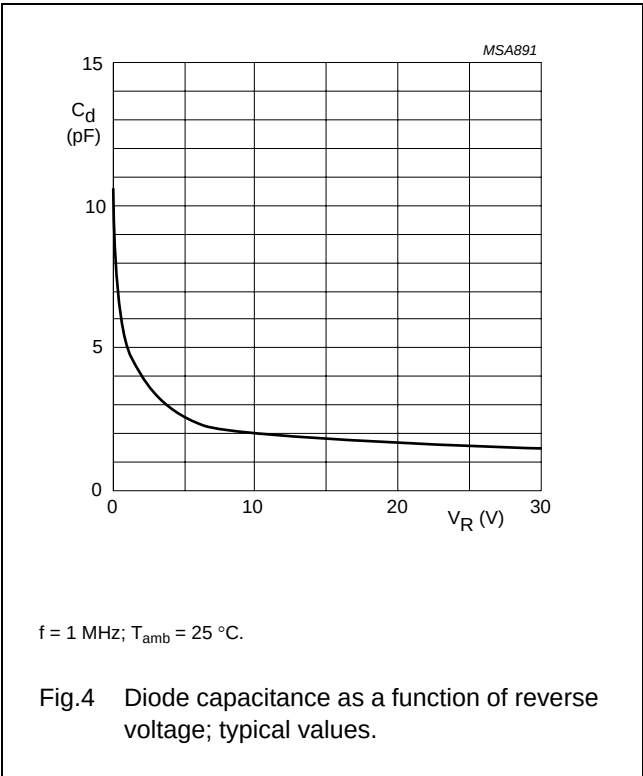
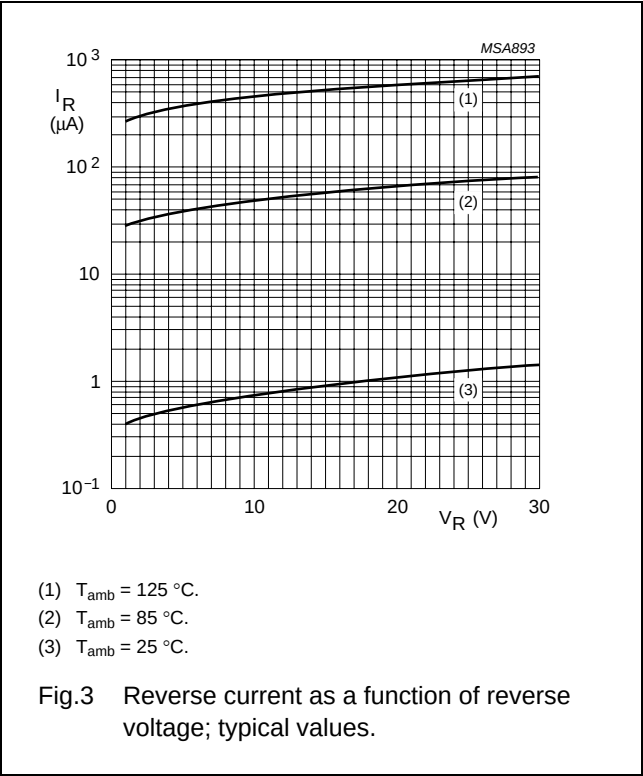
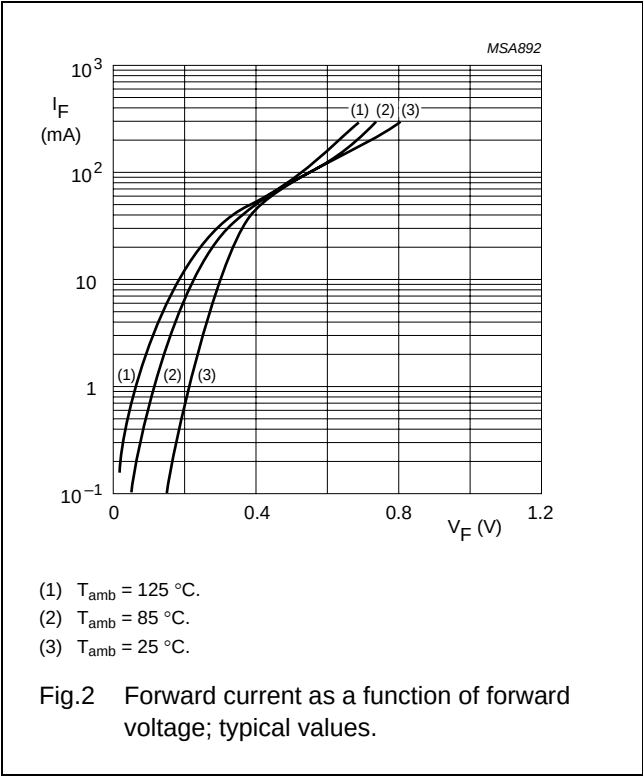
Soldering

Reflow soldering is the only recommended soldering method.

Schottky barrier diode

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GRAPHICAL DATA



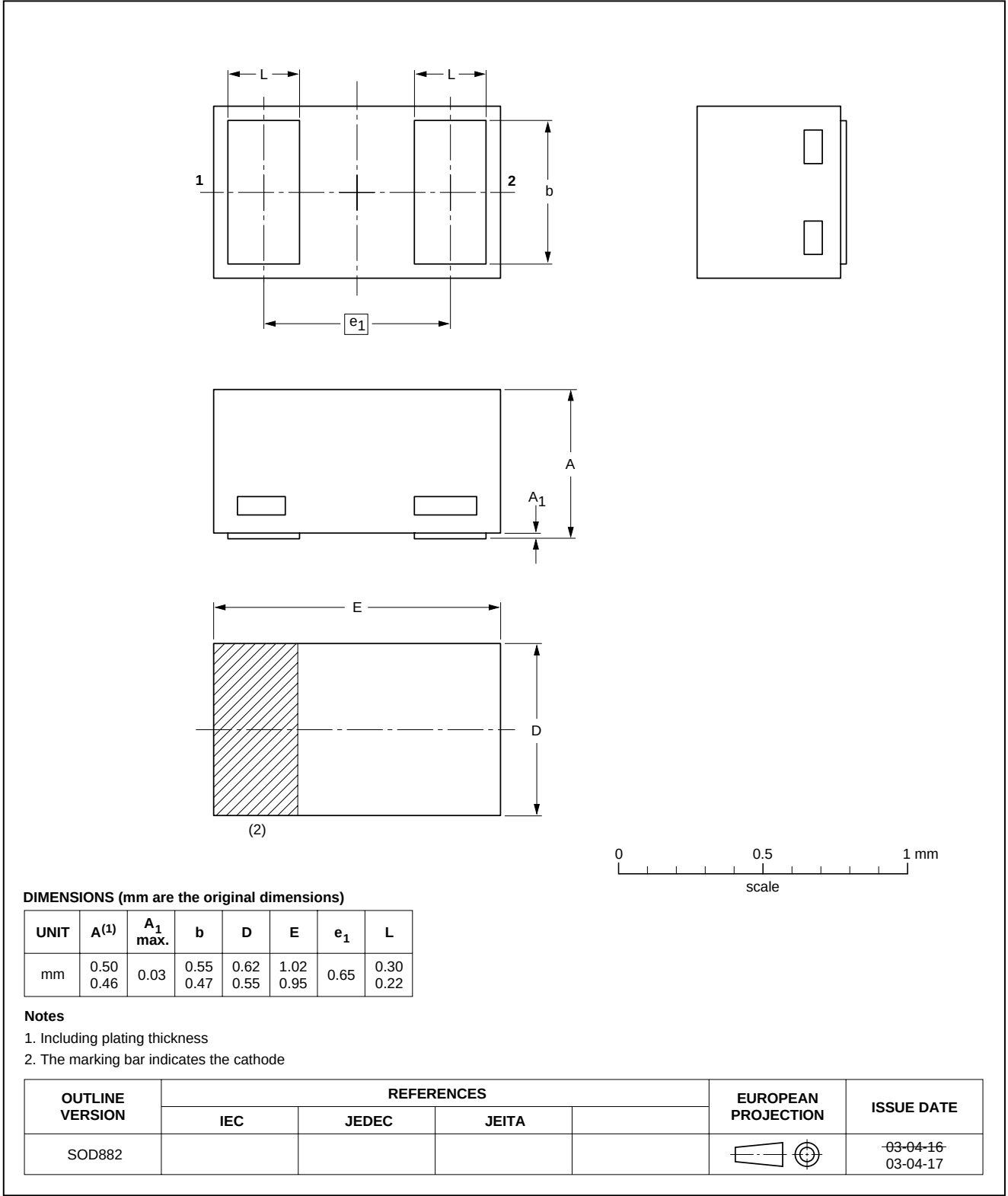
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PACKAGE OUTLINE

Leadless ultra small plastic package; 2 terminals; body 1.0 x 0.6 x 0.5 mm

SOD882



Schottky barrier diode

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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1. Please consult the most recently issued document before initiating or completing a design.
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Printed in The Netherlands

613514/01/pp7

Date of release: 2003 Jun 23

Document order number: 9397 750 11307

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